

FIG.1

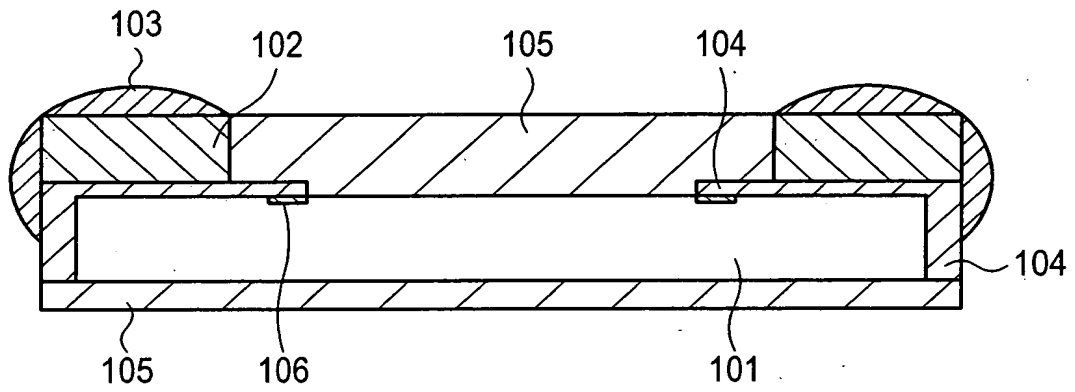


FIG.2

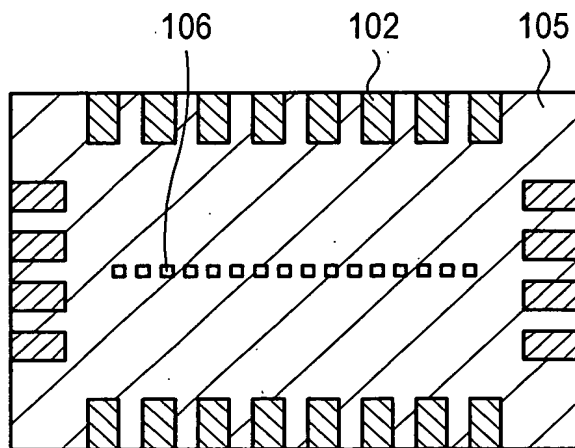


FIG.3

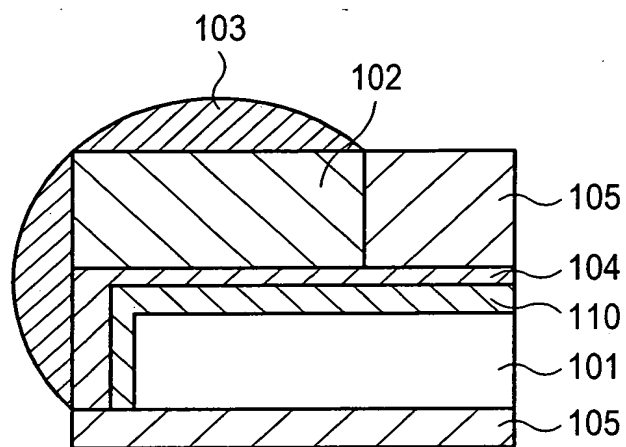


FIG.4

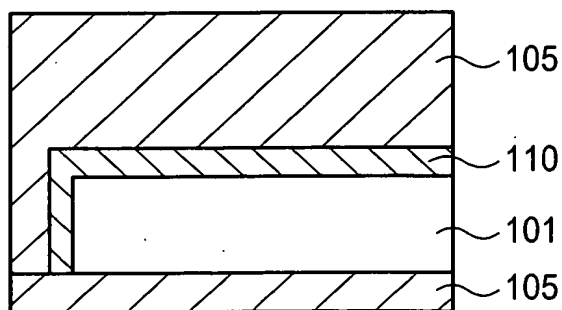
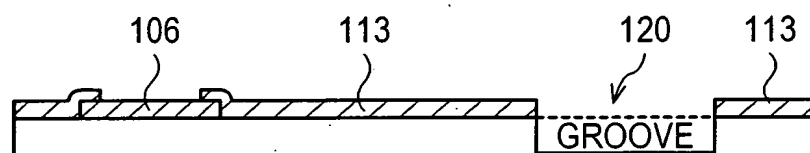
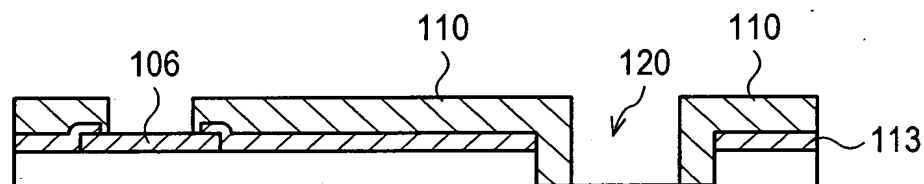
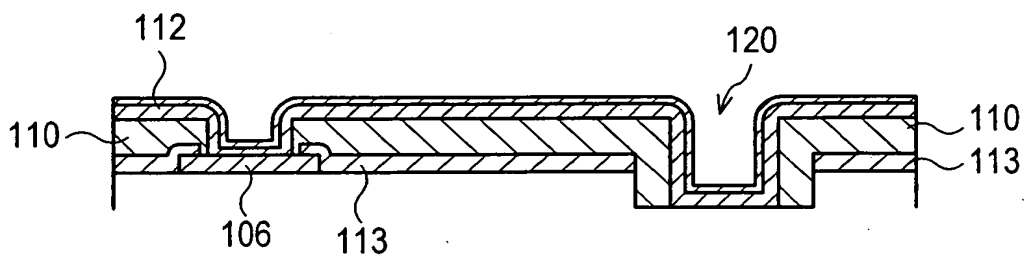


FIG.5(a)

FORMING OF GROOVE

**FIG.5(b)**

FORMING OF INSULATING LAYER

**FIG.5(c)**

FORMING OF METAL FILM



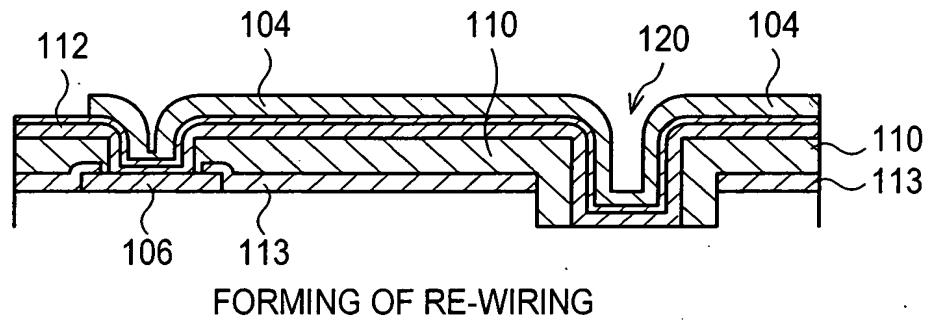
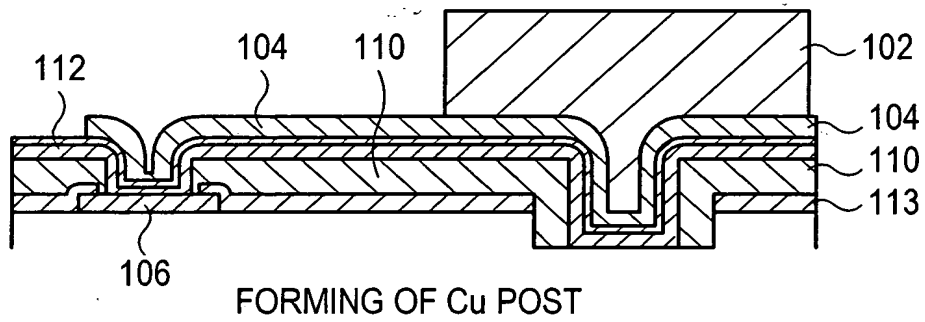
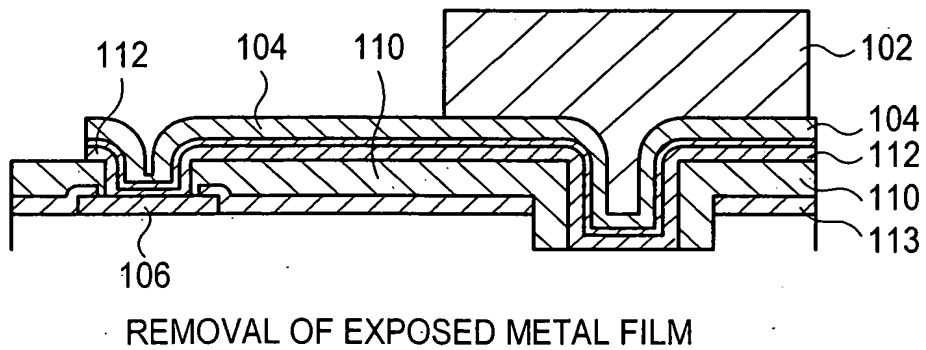
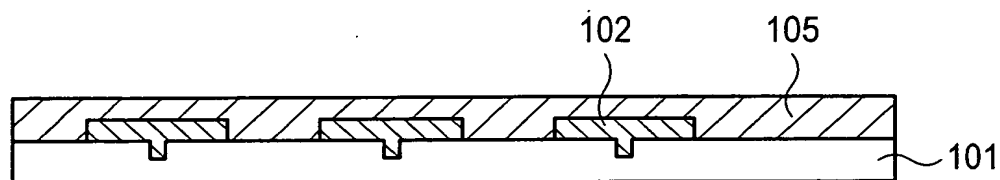
FIG.5(d)**FIG.5(e)****FIG.5(f)**

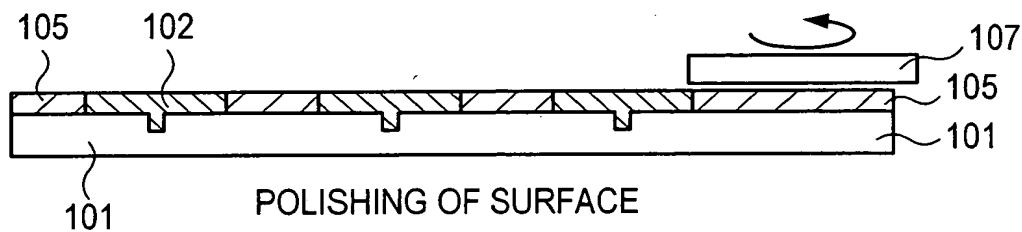
FIG.6(a)



SEALING WITH RESIN



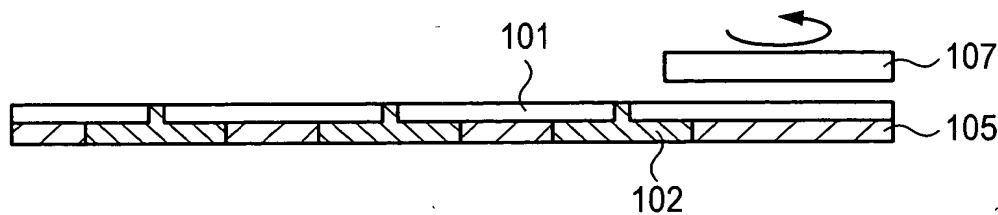
FIG.6(b)



POLISHING OF SURFACE



FIG.6(c)



POLISHING OF BACK SIDE



FIG. 6(a) 5/20

FIG.6(d)

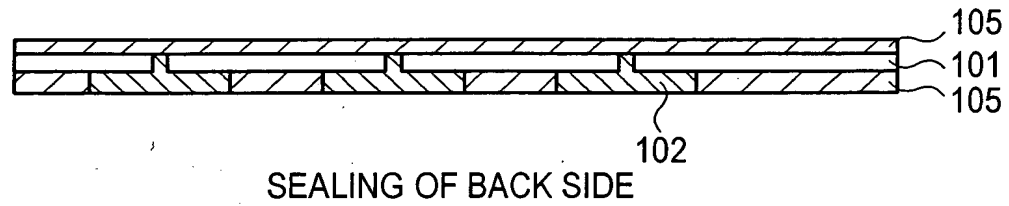


FIG.6(e)

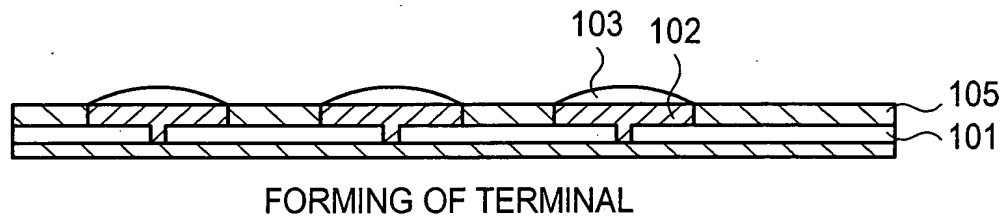


FIG.6(f)



FIG.7(a)

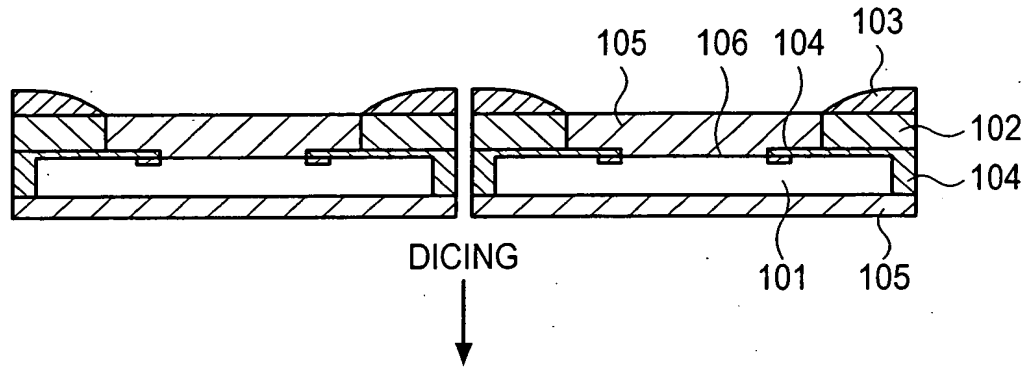


FIG.7(b)

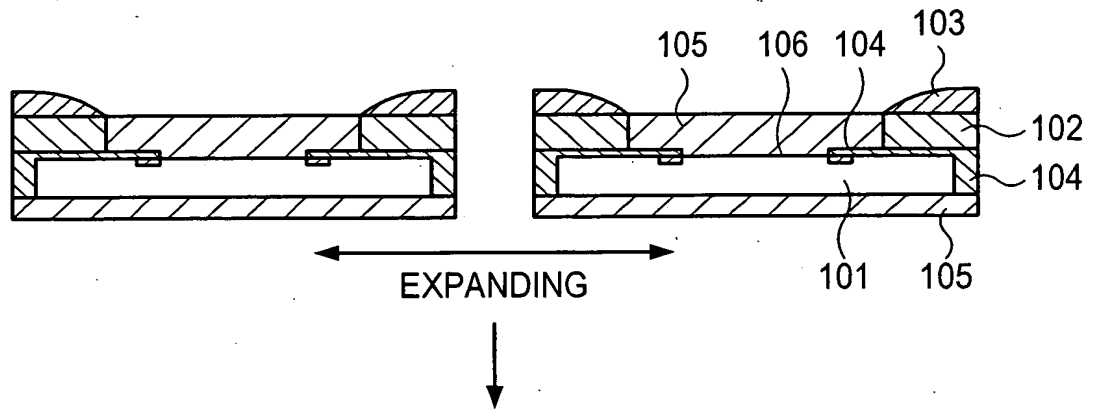


FIG.7(c)

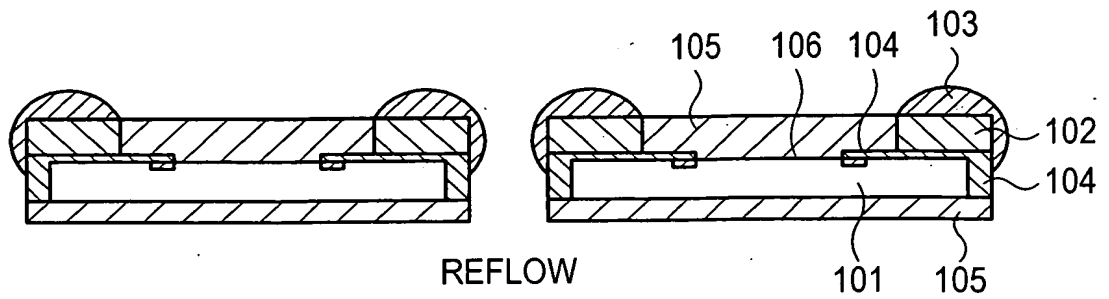


FIG.8

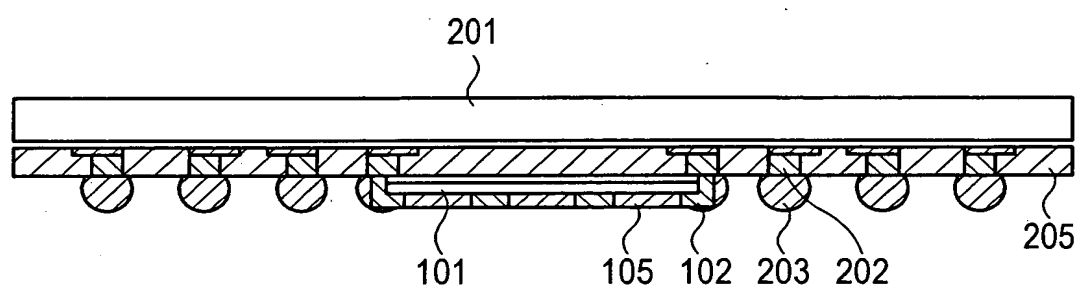


FIG.9

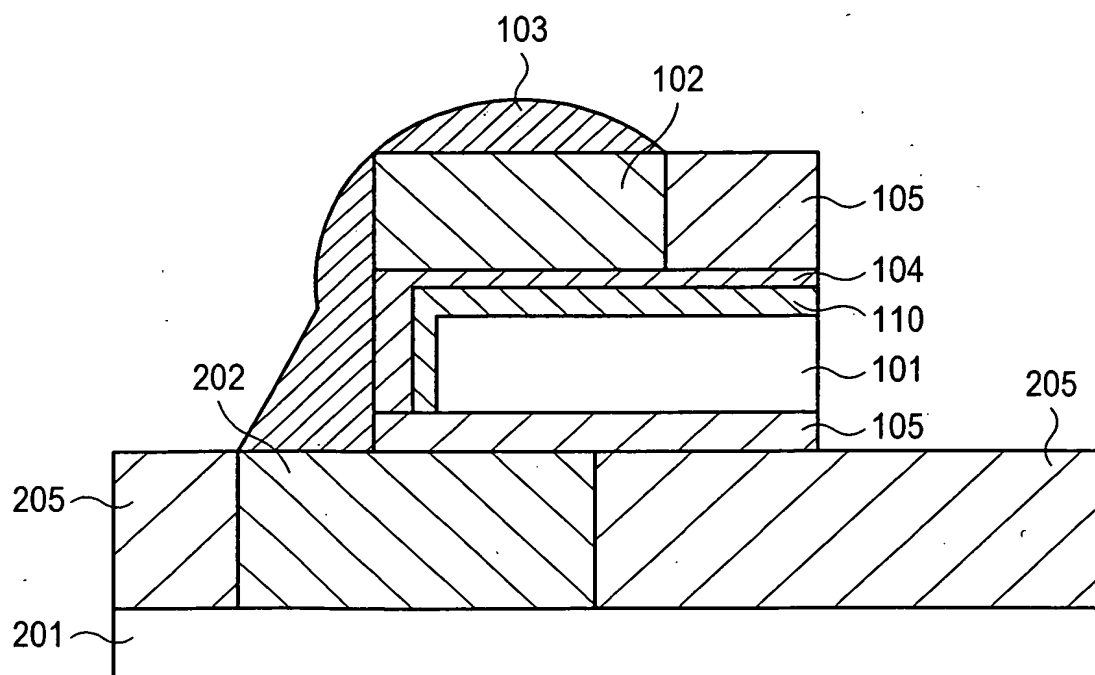


FIG.10

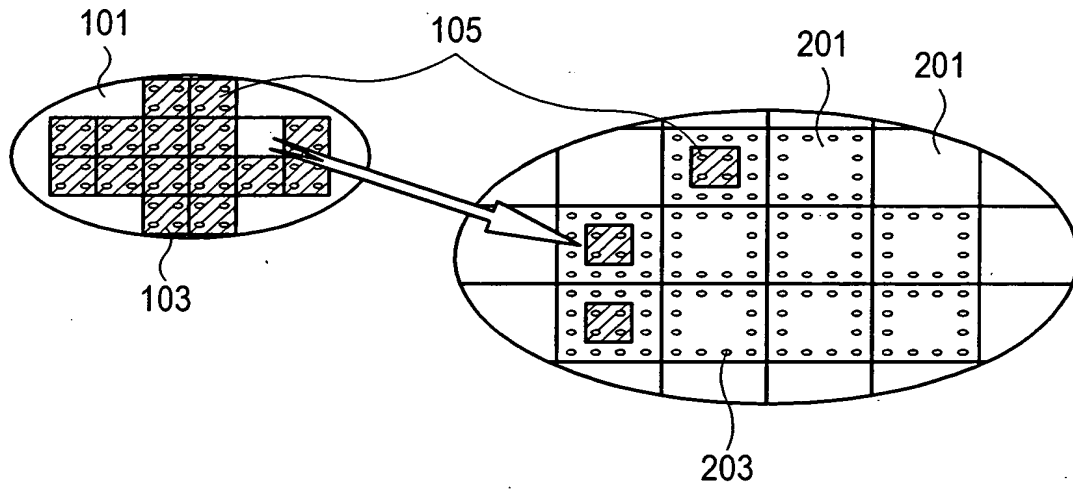


FIG.11

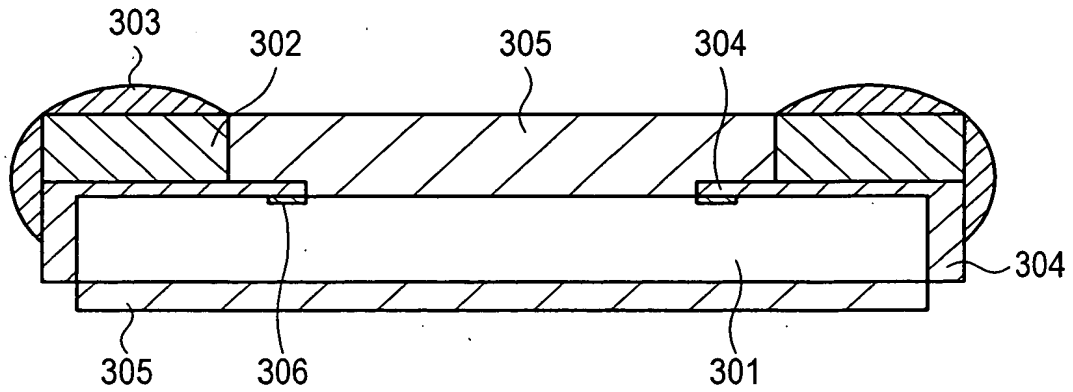


FIG.12

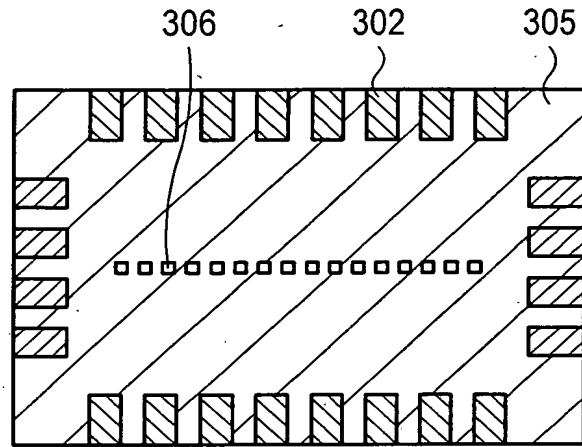


FIG.13

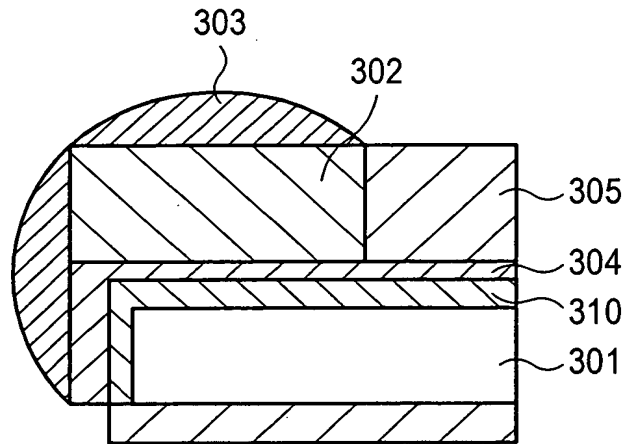


FIG.14

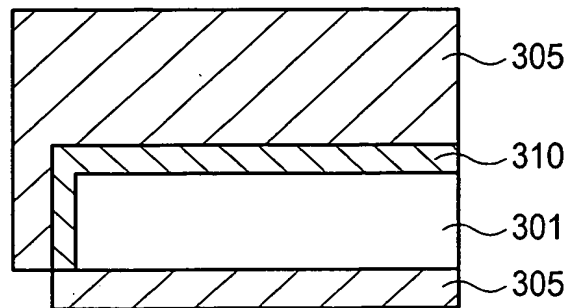
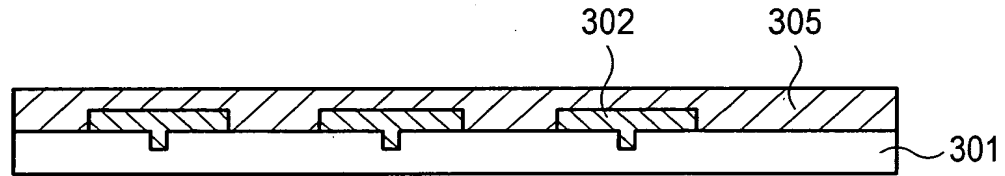


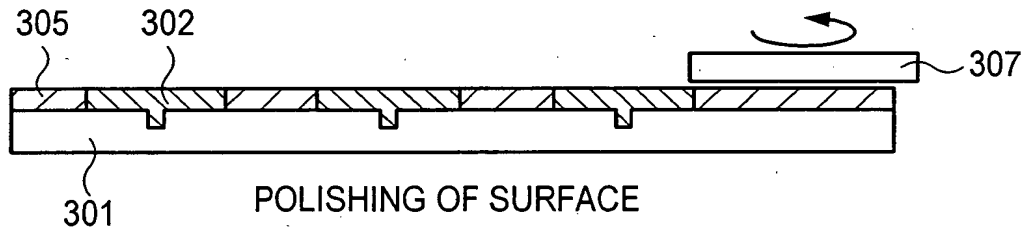
FIG.15(a)



SEALING WITH RESIN



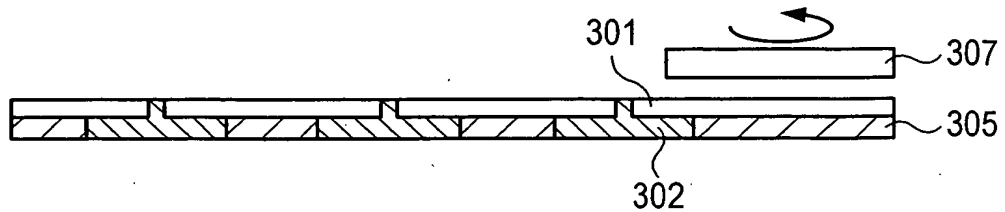
FIG.15(b)



POLISHING OF SURFACE



FIG.15(c)



POLISHING OF BACK SIDE



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FIG.15(d)

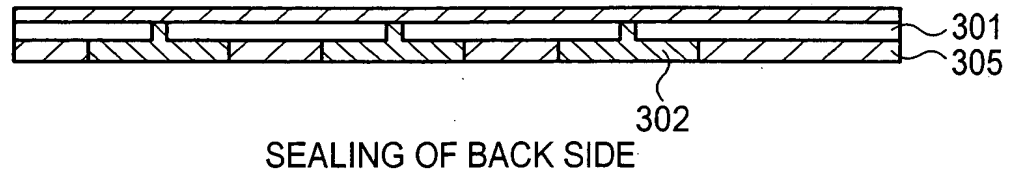


FIG.15(e)

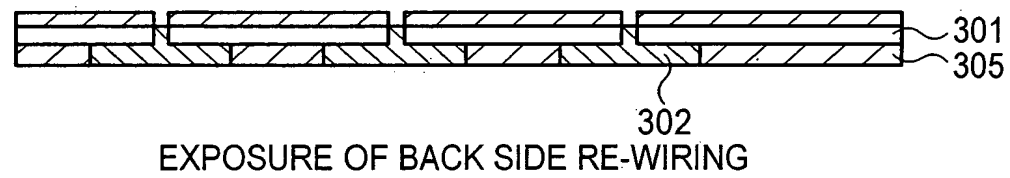


FIG.15(f)

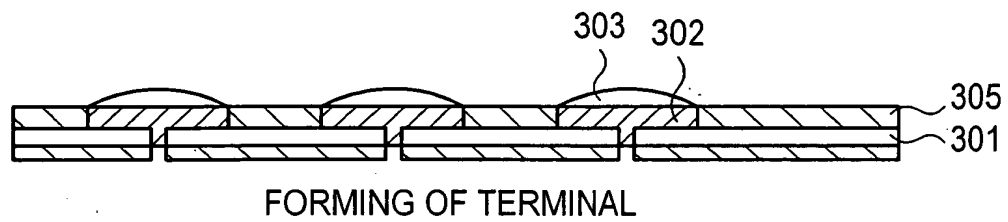


FIG.15(g)

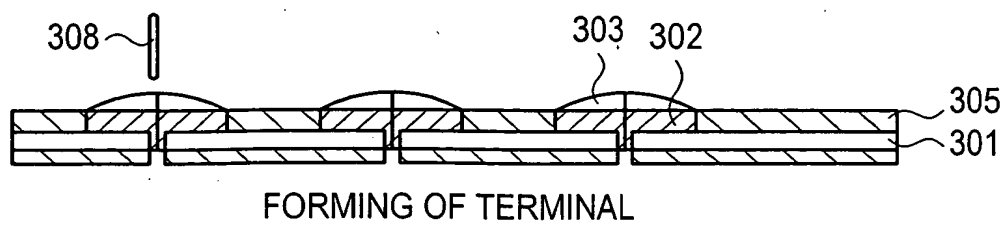


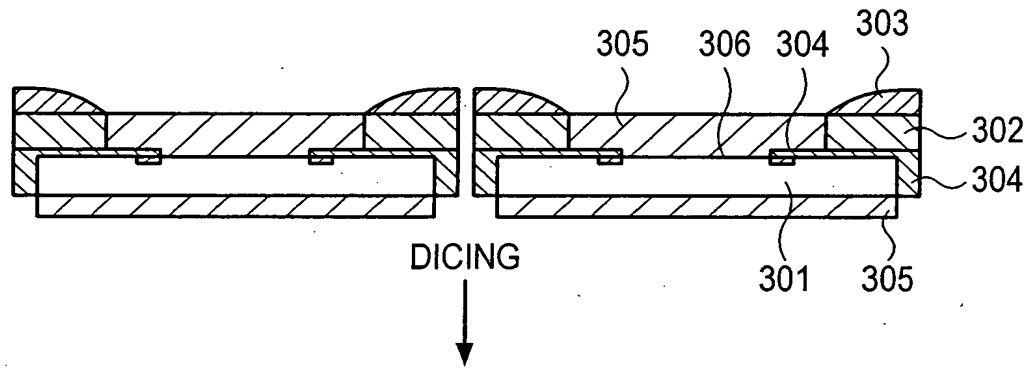
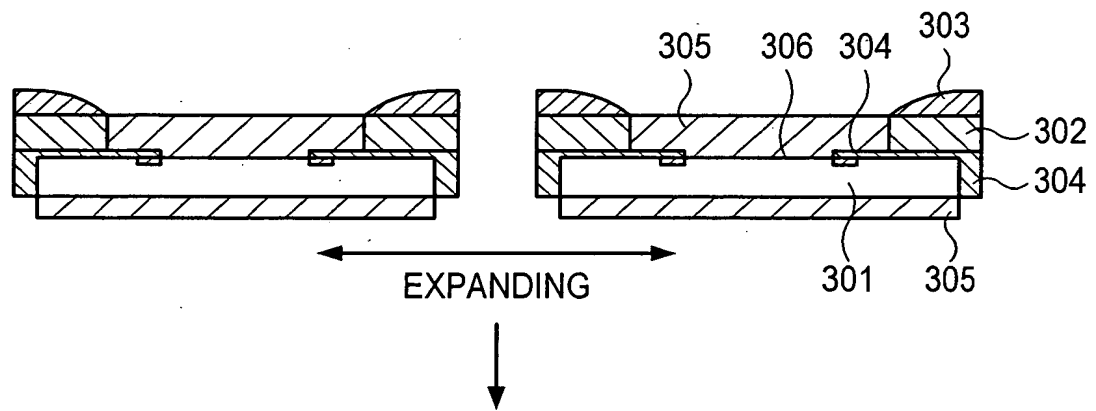
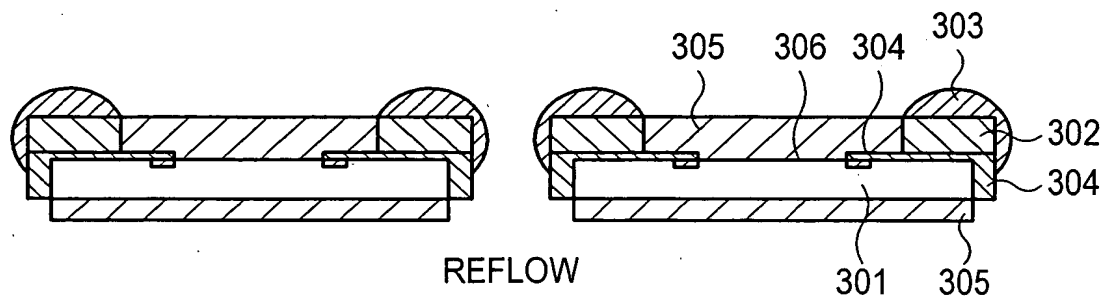
FIG.16(a)**FIG.16(b)****FIG.16(c)**

FIG.17

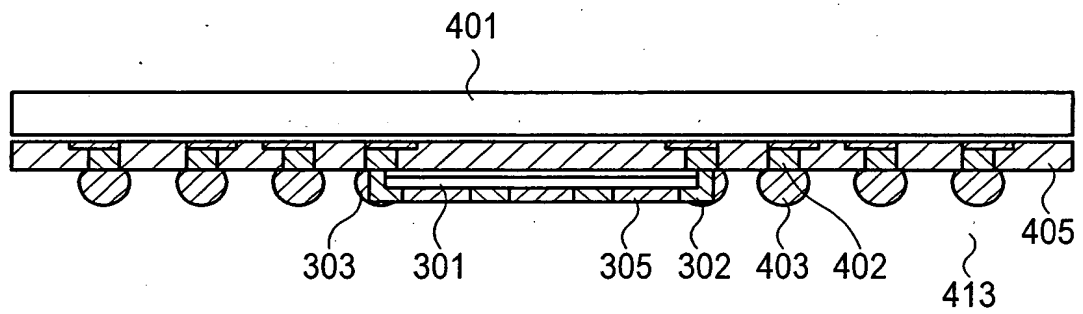


FIG.18

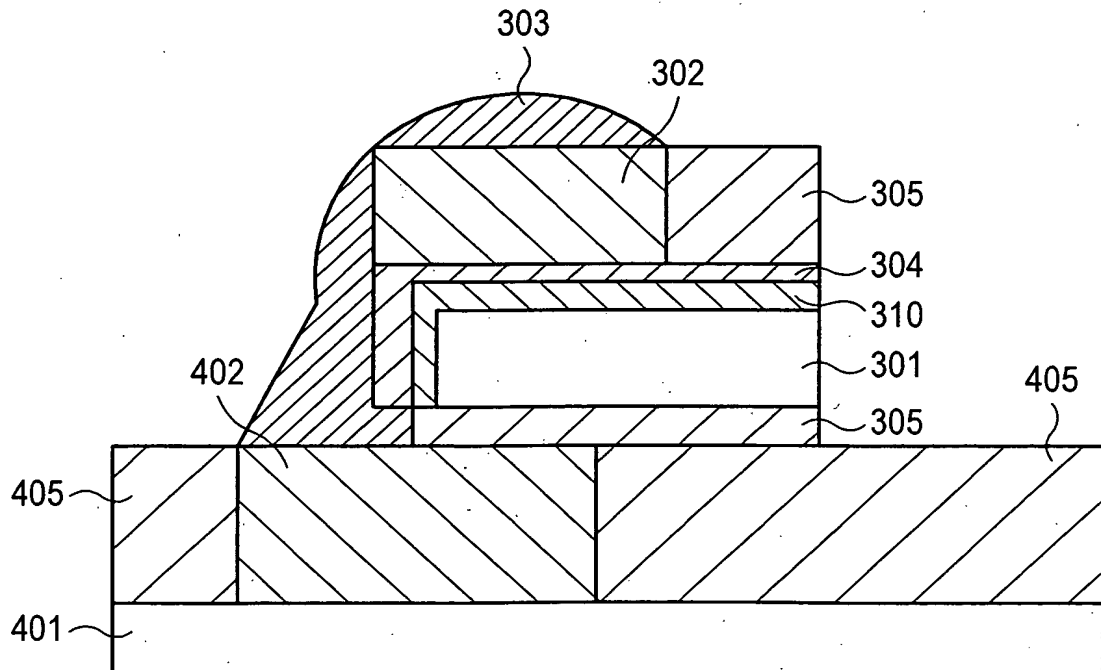


FIG.19

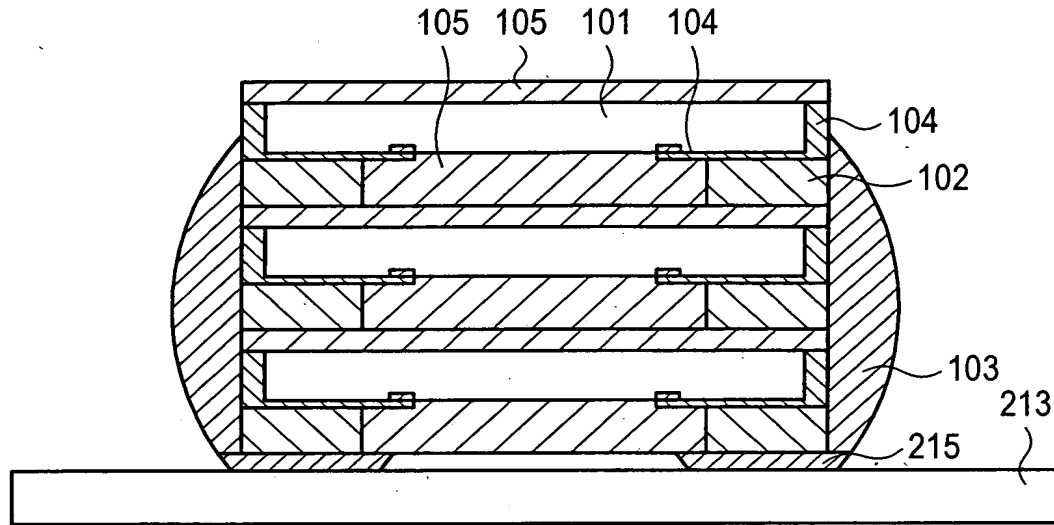


FIG.20

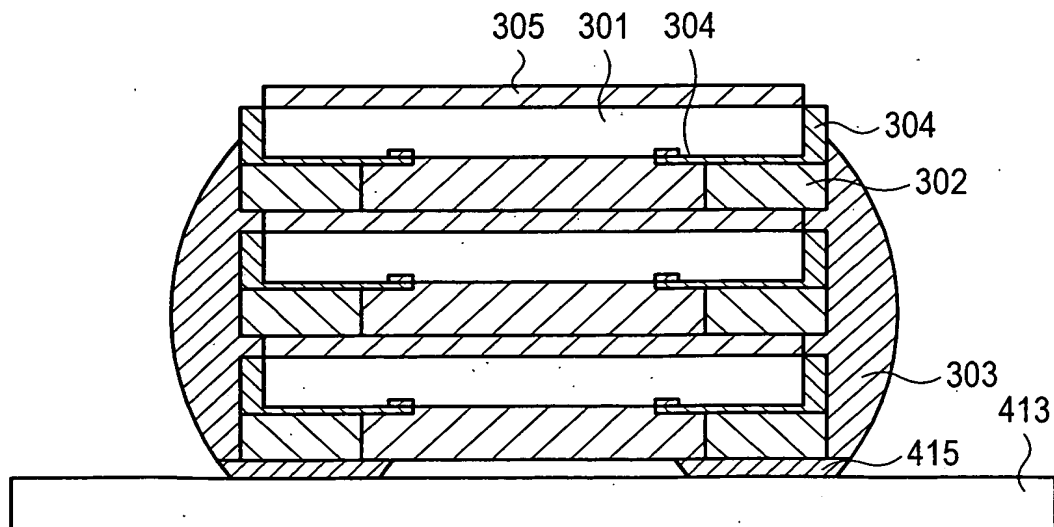


FIG.21

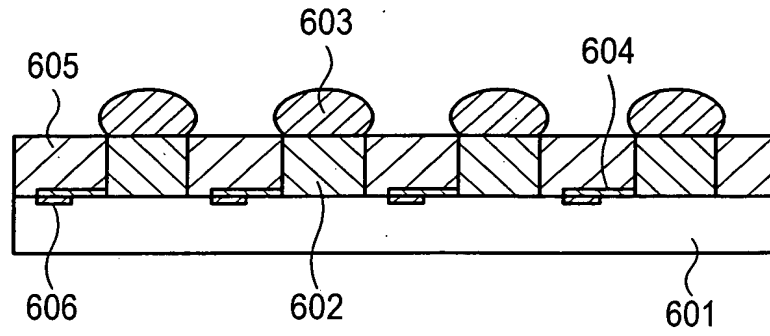


FIG.22

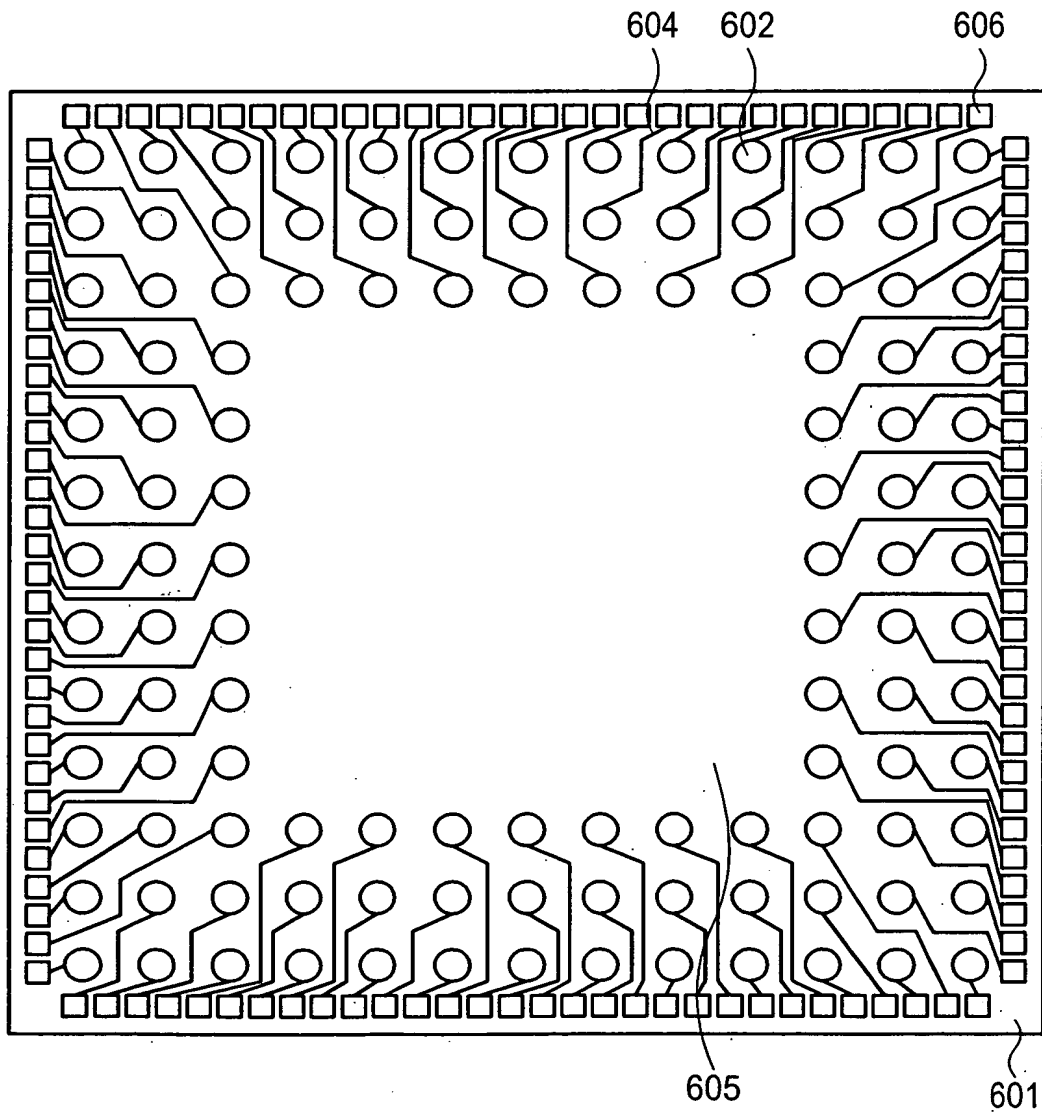


FIG.23(a)

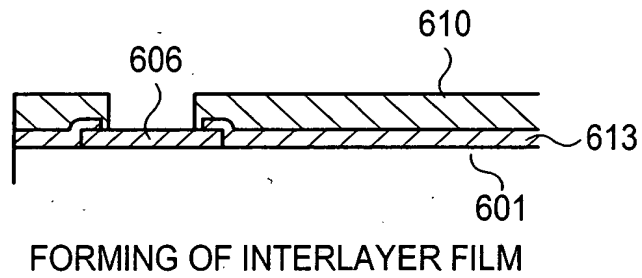


FIG.23(b)

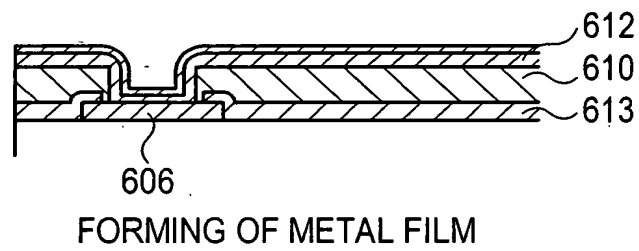


FIG.23(c)

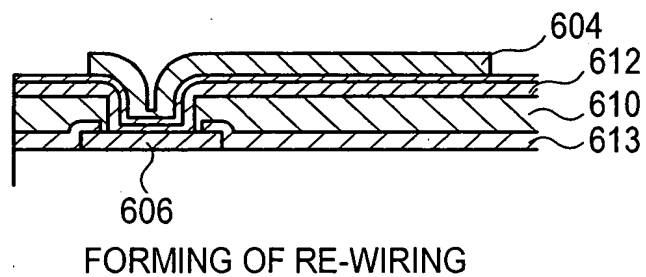
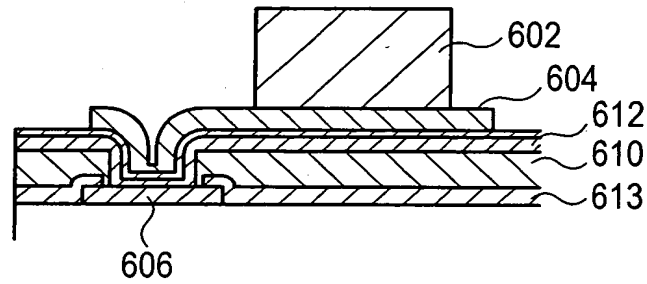
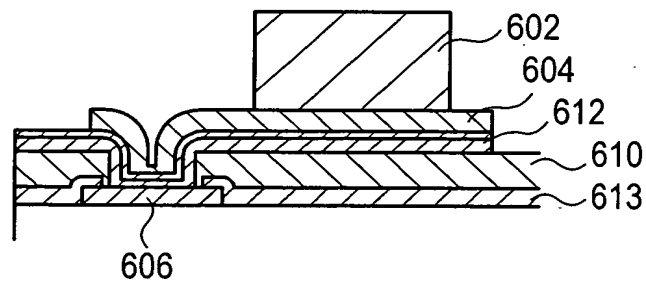
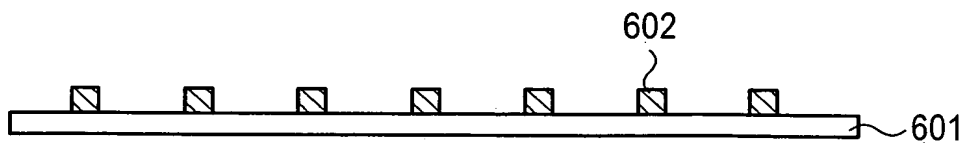


FIG.23(d)

FORMING OF Cu POST

**FIG.23(e)**REMOVAL OF UNNECESSARY
METAL FILM**FIG.24(a)**

FORMING OF Cu POST



FIG.24(b)



FIG.24(c)

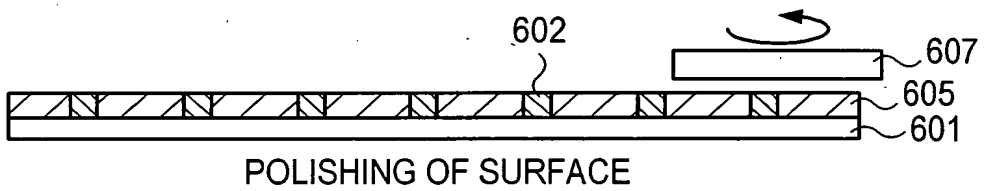


FIG.24(d)

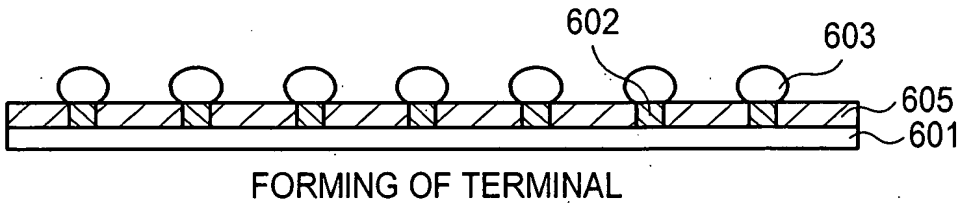


FIG.24(e)

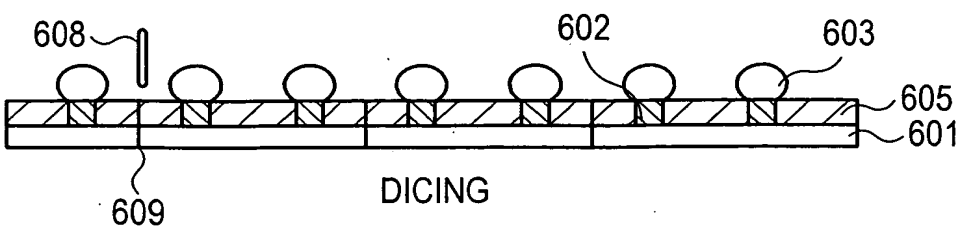


FIG.25

